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## Dual N-Channel 1.5 V (G-S) MOSFET

PRODUCT SUMMARY			
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)
8	0.032 at V <sub>GS</sub> = 4.5 V	4 <sup>a</sup>	7.3 nC
	0.036 at V <sub>GS</sub> = 2.5 V	4 <sup>a</sup>	
	0.045 at V <sub>GS</sub> = 1.8 V	4 <sup>a</sup>	
	0.054 at V <sub>GS</sub> = 1.5 V	4 <sup>a</sup>	

### FEATURES

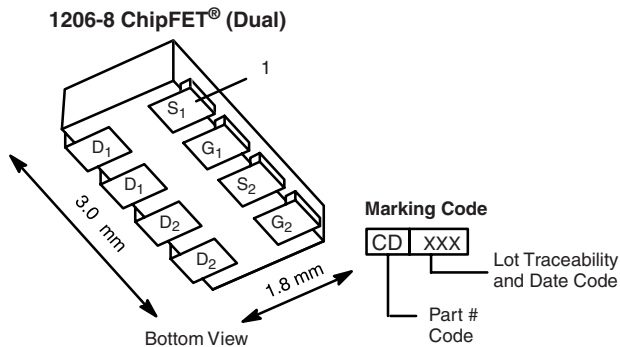
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET<sup>®</sup> Power MOSFET: 1.5 V Rated
- Ultra Low On-Resistance in Compact, Thermally Enhanced ChipFET<sup>®</sup> Package
- Compliant to RoHS Directive 2002/95/EC



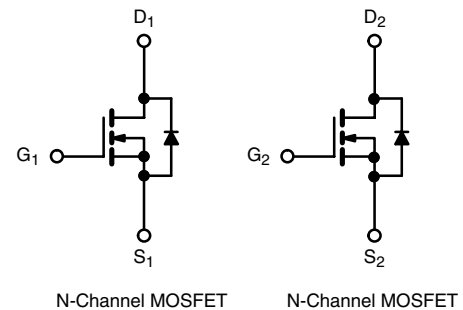
**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**  
Available

### APPLICATIONS

- Load Switch for Portable Applications
- Guaranteed Operation at V<sub>GS</sub> = 1.5 V Critical for Optimized Design and Space Savings



Ordering Information: Si5920DC-T1-E3 (Lead (Pb)-free)  
Si5920DC-T1-GE3 (Lead (Pb)-free and Halogen-free)



ABSOLUTE MAXIMUM RATINGS T <sub>A</sub> = 25 °C, unless otherwise noted			
Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	8	V
Gate-Source Voltage	V <sub>GS</sub>	± 5	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	I <sub>D</sub>	T <sub>C</sub> = 25 °C	4 <sup>a</sup>
		T <sub>C</sub> = 70 °C	4 <sup>a</sup>
		T <sub>A</sub> = 25 °C	4 <sup>a</sup>
		T <sub>A</sub> = 70 °C	4 <sup>a</sup>
Pulsed Drain Current	I <sub>DM</sub>	25	A
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C	
		T <sub>A</sub> = 25 °C	1.7 <sup>c</sup>
Maximum Power Dissipation	P <sub>D</sub>	T <sub>C</sub> = 25 °C	3.12
		T <sub>C</sub> = 70 °C	2.0
		T <sub>A</sub> = 25 °C	2.04 <sup>b, c</sup>
		T <sub>A</sub> = 70 °C	1.3 <sup>b, c</sup>
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C
Soldering Recommendations (Peak Temperature) <sup>d, e</sup>		260	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>b, f</sup>	R <sub>thJA</sub>	50	60	°C/W	
Maximum Junction-to-Foot (Drain)	R <sub>thJF</sub>	30	40		

Notes:

- Package limited.
- Surface mounted on 1" x 1" FR4 board.
- t = 5 s.
- See Solder Profile ([www.vishay.com/ppg?73257](http://www.vishay.com/ppg?73257)). The 1206-8 ChipFET is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.
- Maximum under steady state conditions is 90 °C/W.

SPECIFICATIONS $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0\text{ V}$ , $I_D = 250\text{ }\mu\text{A}$	8			V
$V_{DS}$ Temperature Coefficient	$\Delta V_{DS}/T_J$	$I_D = 250\text{ }\mu\text{A}$		8.2		mV/ $^\circ\text{C}$
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			- 2.6		
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 250\text{ }\mu\text{A}$	0.3		1	V
Gate-Source Leakage	$I_{GSS}$	$V_{DS} = 0\text{ V}$ , $V_{GS} = \pm 5\text{ V}$			$\pm 100$	ns
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 8\text{ V}$ , $V_{GS} = 0\text{ V}$			1	$\mu\text{A}$
		$V_{DS} = 8\text{ V}$ , $V_{GS} = 0\text{ V}$ , $T_J = 55\text{ }^\circ\text{C}$			10	
On-State Drain Current <sup>a</sup>	$I_{D(on)}$	$V_{DS} \leq 5\text{ V}$ , $V_{GS} = 4.5\text{ V}$	25			A
Drain-Source On-State Resistance <sup>a</sup>	$R_{DS(on)}$	$V_{GS} = 4.5\text{ V}$ , $I_D = 6.8\text{ A}$		0.025	0.032	$\Omega$
		$V_{GS} = 2.5\text{ V}$ , $I_D = 6.3\text{ A}$		0.0285	0.036	
		$V_{GS} = 1.8\text{ V}$ , $I_D = 2.5\text{ A}$		0.036	0.045	
		$V_{GS} = 1.5\text{ V}$ , $I_D = 1.8\text{ A}$		0.041	0.054	
Forward Transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = 4\text{ V}$ , $I_D = 6.8\text{ A}$		18		S
<b>Dynamic<sup>b</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 4\text{ V}$ , $V_{GS} = 0\text{ V}$ , $f = 1\text{ MHz}$		680		pF
Output Capacitance	$C_{oss}$			230		
Reverse Transfer Capacitance	$C_{rss}$			140		
Total Gate Charge	$Q_g$	$V_{DS} = 4\text{ V}$ , $V_{GS} = 5\text{ V}$ , $I_D = 6.8\text{ A}$		8	12	nC
		$V_{DS} = 4\text{ V}$ , $V_{GS} = 4.5\text{ V}$ , $I_D = 6.8\text{ A}$		7.3	11	
$Q_{gs}$			0.84			
$Q_{gd}$			1.26			
Gate Resistance	$R_g$	$f = 1\text{ MHz}$		1.8	2.7	$\Omega$
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 4\text{ V}$ , $R_L = 0.73\text{ }\Omega$ $I_D \cong 5.5\text{ A}$ , $V_{GEN} = 4.5\text{ V}$ , $R_g = 1\text{ }\Omega$		8	12	ns
Rise Time	$t_r$			11	17	
Turn-Off Delay Time	$t_{d(off)}$			18	27	
Fall Time	$t_f$			7	11	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Source-Drain Diode Current	$I_S$	$T_C = 25\text{ }^\circ\text{C}$			2.6	A
Pulse Diode Forward Current	$I_{SM}$				25	
Body Diode Voltage	$V_{SD}$	$I_S = 2.6\text{ A}$ , $V_{GS} = 0\text{ V}$		0.8	1.2	V
Body Diode Reverse Recovery Time	$t_{rr}$	$I_F = 2.6\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ , $T_J = 25\text{ }^\circ\text{C}$		12	18	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$			3	5	nC
Reverse Recovery Fall Time	$t_a$			7		ns
Reverse Recovery Rise Time	$t_b$			5		

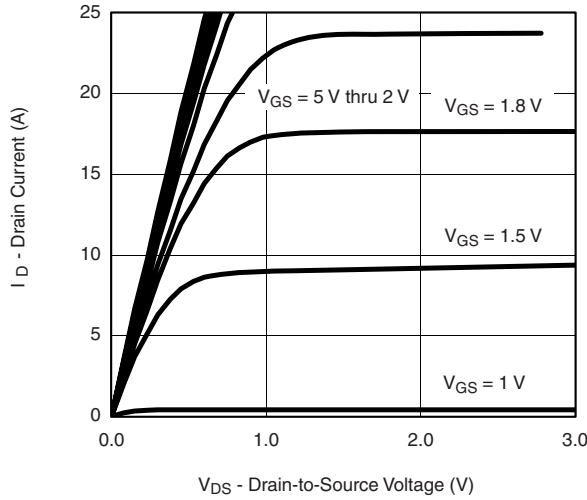
Notes:

- a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .  
b. Guaranteed by design, not subject to production testing.

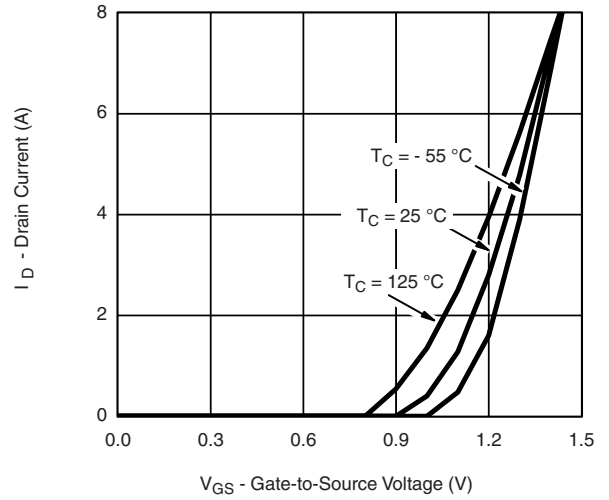
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



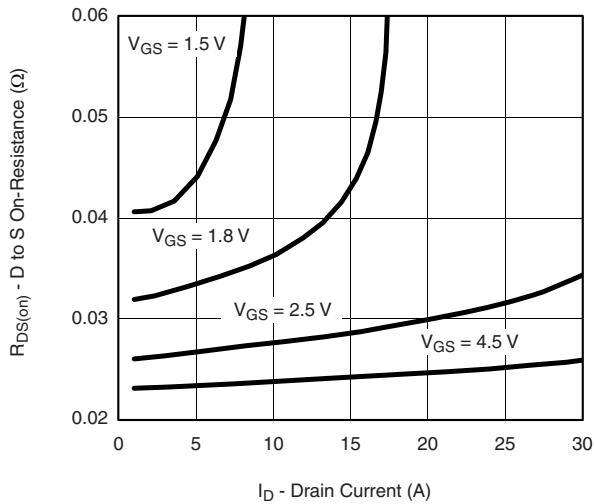
## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



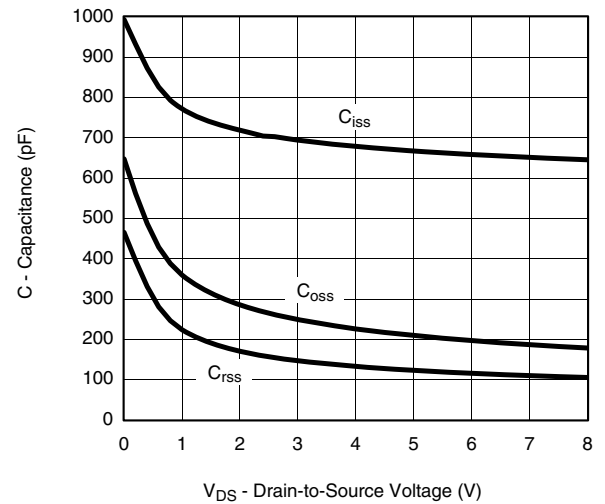
**Output Characteristics**



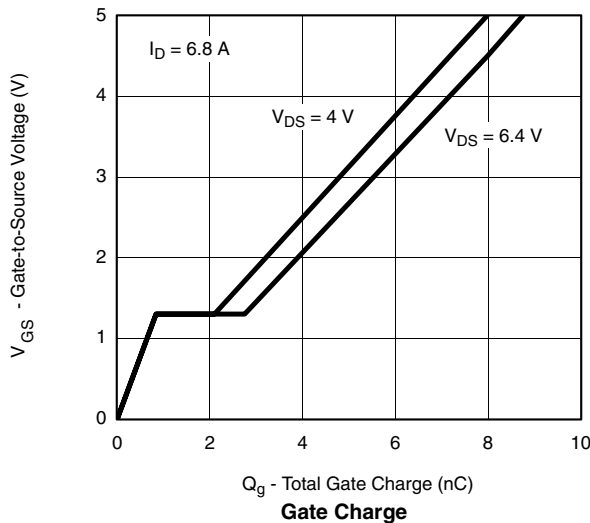
**Transfer Characteristics**



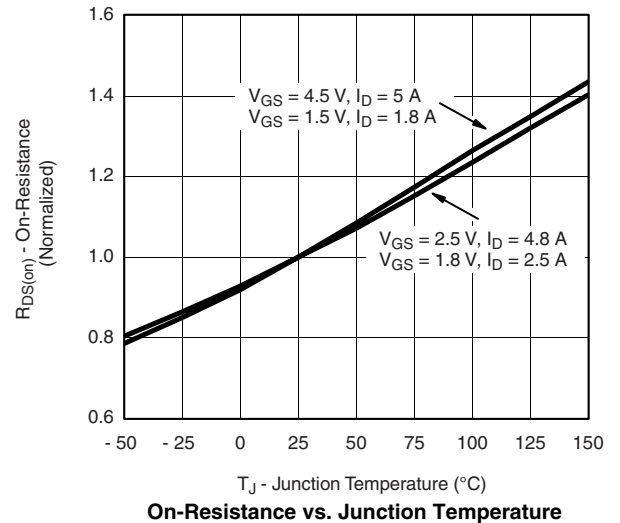
**$R_{DS(on)}$  vs. Drain Current**



**Capacitance**

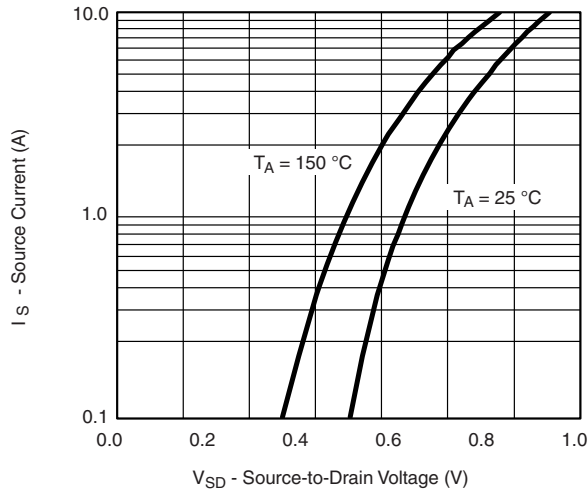


**Gate Charge**

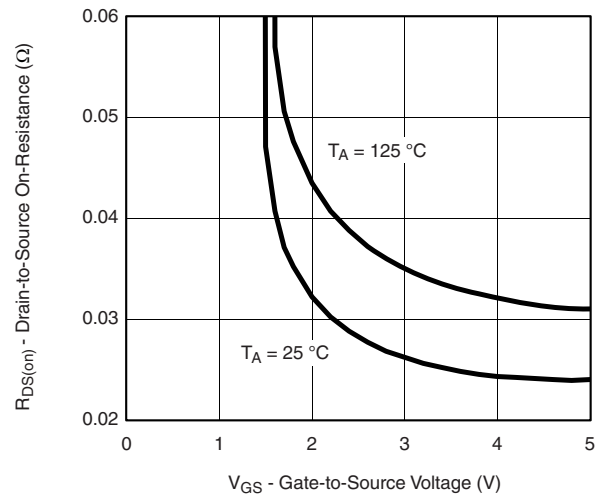


**On-Resistance vs. Junction Temperature**

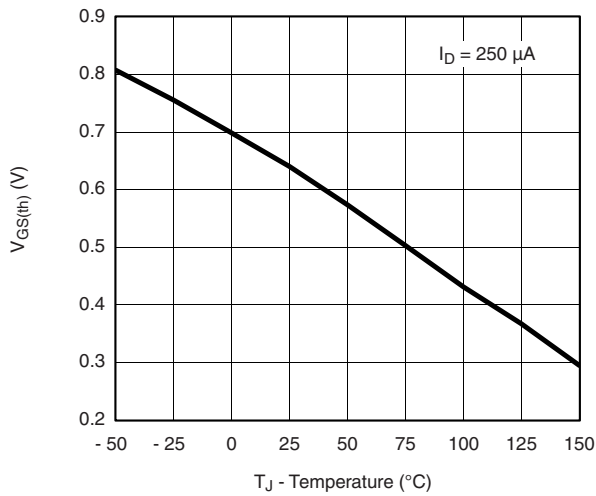
**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted



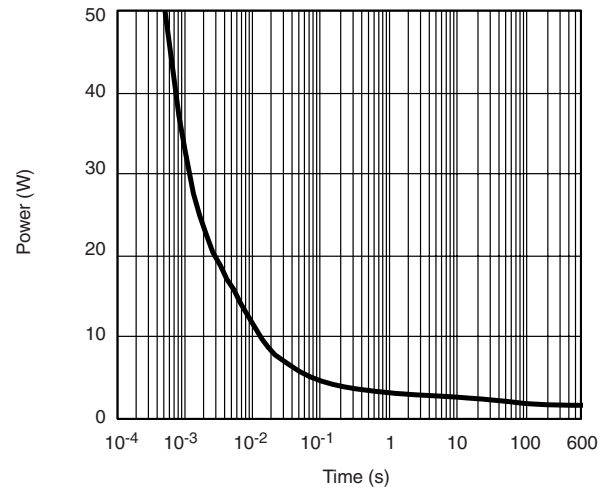
**Forward Diode Voltage vs. Temperature**



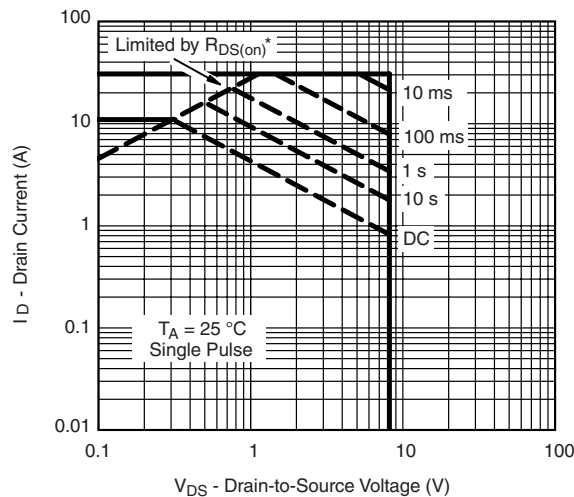
**R<sub>DS(on)</sub> vs. V<sub>GS</sub> vs. Temperature**



**Threshold Voltage**



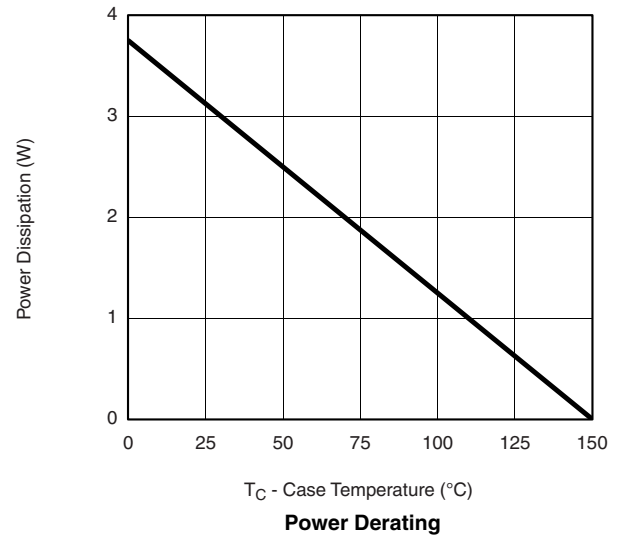
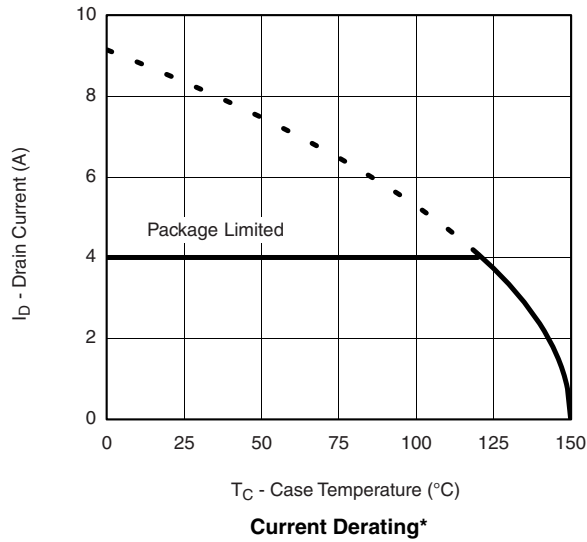
**Single Pulse Power**



\* V<sub>GS</sub> > minimum V<sub>GS</sub> at which R<sub>DS(on)</sub> is specified

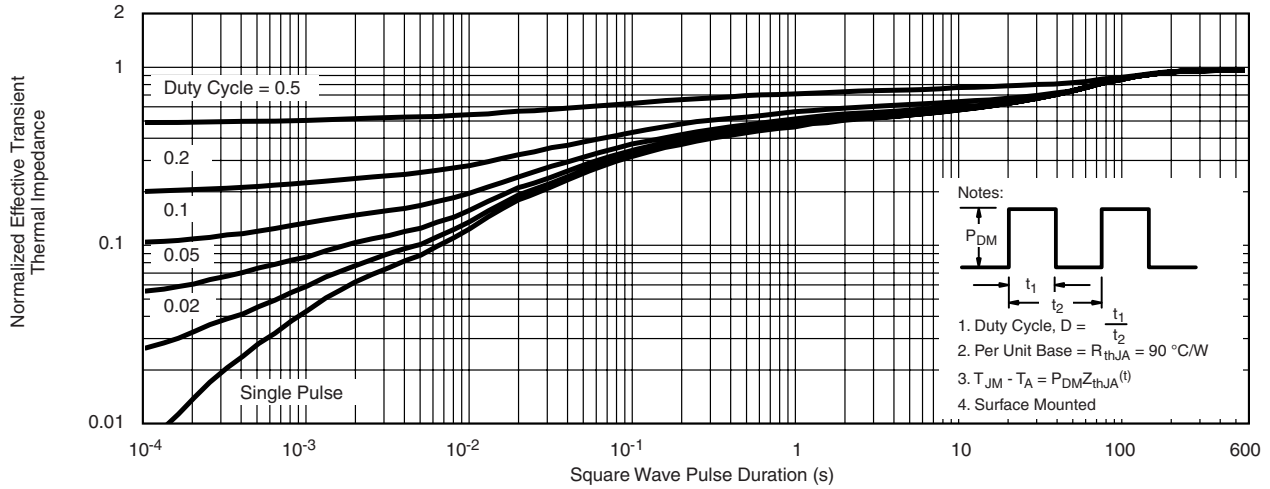
**Safe Operating Area, Junction-to-Case**

**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted

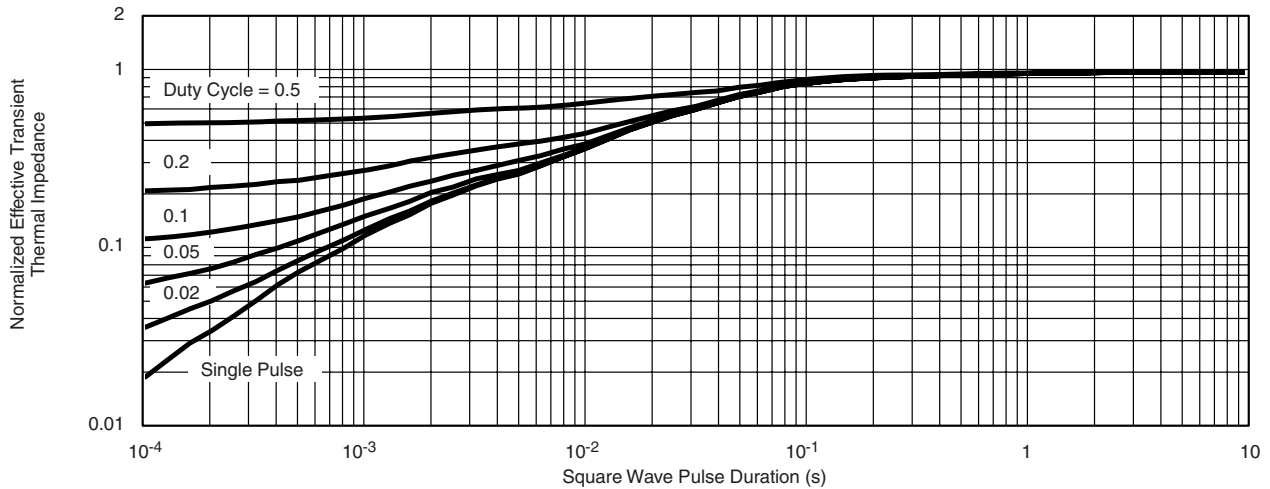


\* The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted



**Normalized Thermal Transient Impedance, Junction-to-Ambient**



**Normalized Thermal Transient Impedance, Junction-to-Foot**

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